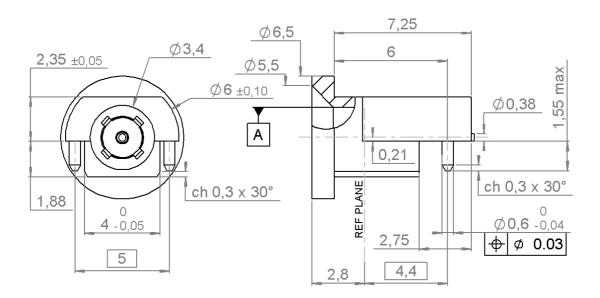
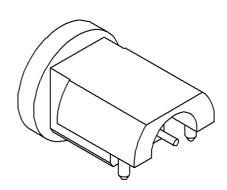
SOLDER LEGS - CATCHER'S MITT

R222.680.710

Series : SMP







All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	STAINLESS STEEL BERYLLIUM COPPER - PTFE -	GOLD 0.5 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2 -	
-	-	-	

Issue: 1423 A

In the effort to improve our products, we reserve the right to make changes judged to be

necessary.



SOLDER LEGS - CATCHER'S MITT

R222.680.710

Series: SMP

PACKAGING

Standard	Unit	Other
500		Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω Frequency **0-12** GHz

VSWR $1.25 + 0.0100 \times F(GHz) Maxi$

Insertion loss **0.15** $\sqrt{F(GHz)}$ dB Maxi RF leakage **NA** - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage 500 Veff mini Insulation resistance **5000** MΩ mini

ENVIRONMENTAL

-65/+165 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end **6.7** N mini Axial force – Opposite end **6.7** N mini Torque NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 1000 Cycles mini

Weight **0,8730** g

Issue: 1423

In the effort to improve our products, we reserve the right to make changes judged to be



R222.680.710

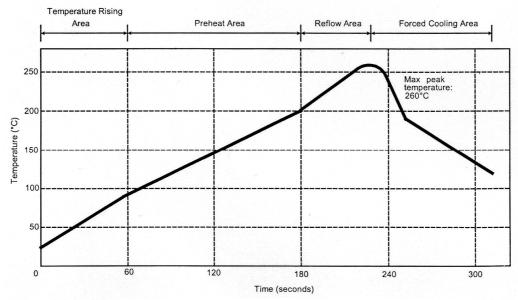
SOLDER LEGS - CATCHER'S MITT

Series: SMP

SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 µm. Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 - Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 1423 A In the effort to improve our products, we reserve the right to make changes

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



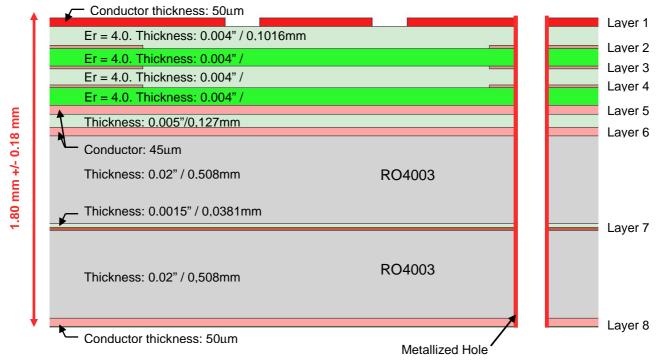
SOLDER LEGS - CATCHER'S MITT

R222.680.710

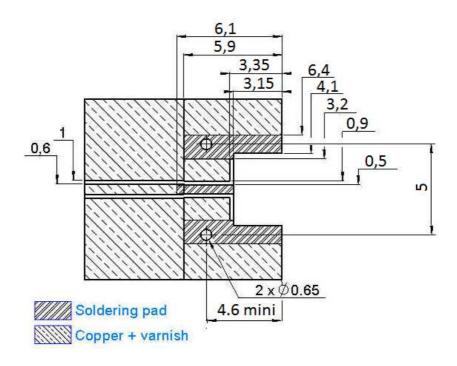
Series: SMP

RECOMMENDED PAD DIMENSIONS:

Substrate: add vias between both sides along upper ground plane according to engineering practise



Conductor thickness: ½oz./17.5um unless specified otherwise



Issue: 1423 A In the effort to improve our products, we reserve the right to make changes judged to be necessary.

